

Announcement and Call for Abstracts

IMAPS and SEMI Proudly announce a Joint Topical Workshop on *Advanced Interconnect Technologies*

www.imaps.org/advintercon

*This event will be co-located with [IMAPS Workshop on Wire Bonding](#)
and with [SEMICON West 2010](#)*

July 14, 2010

Moscone Center

San Francisco, California - USA

Still Accepting Abstracts

Chairs:	
Anwar Mohammed, Huawei Technologies amohammed@huawei.com	Zhihao Yang, NanoMas Technologies zhihao.yang@nanomastech.com

Workshop Focus:

The **Advanced Interconnect Technologies Workshop** has been organized to allow for the presentation and debate of some of the latest interconnect and processing technologies in Electronic Packaging. Sessions and presentations are planned around (but not limited to) the following topics:

- Nano Printing Technology and Optointerconnect
- Integration of Packaging and Semiconductor Technology
- Nano Materials Applications in Electronic Packaging Industry
- 3D ICs Interconnect Technologies
- Wafer Level Chip Scale Packaging
- Printed Electronics

Those wishing to present a paper at the Advanced Interconnect Technologies Workshop must submit a 200-300 word abstract electronically using the on-line submittal form at: www.imaps.org/abstracts.htm. Full written papers are not required; however, an extended abstract of 1-4 pages is due for accepted presenters no later than June 18, 2010.

The Microelectronics Foundation sponsors Student Paper Competitions in conjunction with all Advanced Technology Workshops (ATWs) and Conferences. Students submitting their work and identifying that "**Yes, I'm a full-time student**" on the abstract submission form; will automatically be considered for these competitions. The review committee will evaluate all student papers/posters and award at least one student author with a \$1,000 check at the ATW/Conference. The selected student must attend the event to present his or her work and receive the award. The Foundation will return the registration fee for the winner. The winner must pay for travel and lodging expenses.

Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 202-548-4001 if you have questions.

Accepted papers may be considered for publication in the IMAPS *Journal of Microelectronics and Electronic Packaging*. **All Speakers are required to pay a reduced registration fee and are required to attend the entire event.**

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